



Media Alert

April 10, 2008

MEDIA ALERT

AMBRIC FELLOW, MIKE BUTTS, TO PRESENT PAPER AT IEEE FCCM

WHO: Mike Butts, an Ambric®, Inc. Fellow and the lead hardware architect

WHAT: Mr. Butts will present the paper he co-authored with Ambric's Brad Budlong, Paul Wasson and Ed White. The paper is entitled "**Reconfigurable Work Farms on a Massively Parallel Processor Array.**"

WHEN: Tuesday, April 15 in Session 7: Processor-based Architectures

WHERE: The IEEE Field-Programmable Custom Computing Machines (FCCM) Conference at the Stanford University Alumni Center, Palo Alto, Calif.

URL: <http://www.fccm.org/>

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About Ambric, Inc.

Ambric is a fabless semiconductor company delivering the world's first TeraOPS-class device and software development tools that make massively parallel software programming practical for complex embedded systems. The company's highly scalable, massively parallel processor arrays (MPPAs) deliver performance that is more than an order of magnitude greater than high-end digital signal processors (DSPs) and provides a programming model that is much easier than what is available for multiple-DSP platforms. The price-performance exceeds that of field-programmable gate arrays (FPGAs) for complex applications, while enabling faster, easier development in software. Ambric products help companies accelerate time-to-market for their solutions while slashing their system development costs.

Established in 2003 and headquartered in Beaverton, Ore., Ambric has received funding from ComVentures, OVP Venture Partners, Northwest Technology Ventures, and private investors. Visit <http://www.ambric.com> for the latest news and information on the company

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